

ABSTRACT OF THE DISCLOSURE

A protective film forming apparatus for forming a protective film on the subject surface of a wafer. The protective film forming apparatus includes a spinner table for holding the wafer thereon under suction vacuum and rotating the wafer in a held condition thereof and resin applying means for applying a liquid resin to the wafer held on the spinner table. The resin applying means includes spraying means for spraying the liquid resin, an arm for supporting the spraying means, and swinging means for horizontally swinging the spraying means supported to the arm in a minimum required range from the center of rotation of the wafer to the outer circumference of the wafer.

FIG. 7